



# Product Change Notification

**Change Notification #:** 837393-01

**Change Title:** Select Intel® Ethernet Network Adapter X710-T2L  
**Reason for Revision: Year input error: The “Date Customer Must be Ready to Receive Post-Conversion Material (RTR Date)” should be December 6, 2024, instead of December 6, 2025**

**Change Detail:** Update Heatsink Thermal Gap Filler Material & EU Single Place of Contact Address on Labels

**Date of Publication:** February 12, 2025

## Key Characteristics of the Change:

Product Material, Label

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material</b>	December 06, 2024
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## Description of Change to the Customer:

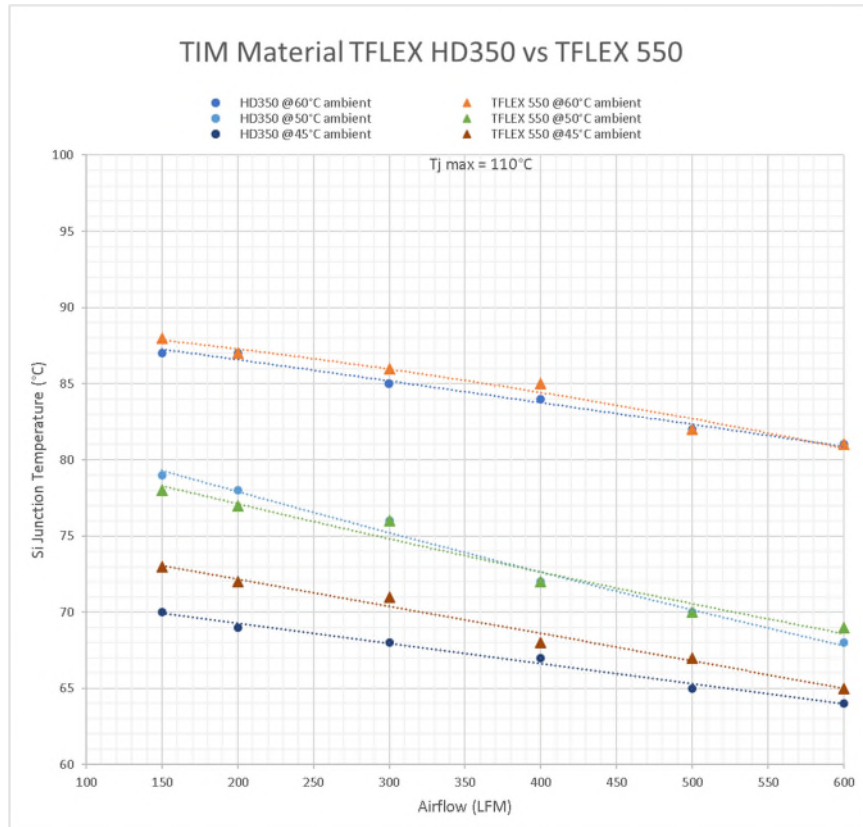
**Reason for Revision: Year input error: The “Date Customer Must be Ready to Receive Post-Conversion Material (RTR Date)” should be December 6, 2024, instead of December 6, 2025**

The Intel® SKUs listed in the products affected table below will be updated with the following change(s):

1. The thermal gap filler material used on the Intel® Ethernet Network Adapter X710-T2L has been discontinued and is being replaced with a new material.

<b>Material properties differences</b>	<b>Previous Gap Filler TFLEX 550</b>	<b>New Gap Filler HD350</b>
Thermal Conductivity (W/mK)	2.8	2.7
Hardness (Shore 00)	40	38
Density (g/cc)	3.0	3.1
Temperature Range	-50°C to 200°C	-40°C to 200°C
Construction material	Filled Silicone elastomer	Ceramic Filled Silicone sheet
Thermal Conductivity (W/mK)	2.8	2.7

The new material has been tested and confirmed to meet the thermal requirements of the product. A chart comparing the thermal performance of the previous and new gap filler material is shown below.



- The European Union (EU) Single Place of Contact (SPOC) address that is printed on the disti label will be updated on all of the products listed in Products Affected/Intel Ordering Codes table. The new address is shown below.

EU Single Place of Contact:

Intel Deutschland GmbH, z. H. Corp. Quality,  
Dornacher Str. 1, 85622 Feldkirchen, Germany

Marketing Name	Product Code	MM#	Label Type
Intel® Ethernet Network Adapter X710-T2L	X710T2L	984697	B, C
Intel® Ethernet Network Adapter X710-T2L	X710T2LBLK	984713	A
Intel® Ethernet Network Adapter X710-T2L	X710T2LG1P5	984718	A





As a result of these changes, the Printed Board Assembly (PBA) and Top Assembly (TA) numbers will roll as noted in the affected products table within this PCN notice. If the PBA/TA numbers are printed on any product or box labels, those will show the PBA/TA dash roll as well.

### Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers.

Customers can expect to receive mixed inventory until current inventory levels are depleted.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

### Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
Intel® Ethernet Network Adapter X710-T2L	X710T2LBLK	984713	K57897-009	K37379-009	K57897-010	K37379-010
Intel® Ethernet Network Adapter X710-T2L	X710T2LG1P5	984718	K38324-009	K29823-013	K38324-010	K29823-014
Intel® Ethernet Network Adapter X710-T2L	X710T2L	984697	K57893-009	K37379-009	K57893-010	K37379-010

### PCN Revision History:

Date of Revision:	Revision Number:	Reason:
October 30, 2024	00	Originally Published PCN
February 12, 2025	01	Year input error: The “Date Customer Must be Ready to Receive Post-Conversion Material (RTR Date)” should be December 6, 2024, instead of December 6, 2025



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## 837393-01

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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apacgccb@intel.com](mailto:apacgccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

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